## 501840455 03/02/2012

## PATENT ASSIGNMENT

## Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date	
Shiang-Ruei SU	03/01/2012	
Liang-Chen LIN	03/01/2012	
Chia-Wei TU	03/01/2012	

#### **RECEIVING PARTY DATA**

Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
Street Address:	No. 8, Li-Hsin Rd. VI, Hsinchu Science Park
City:	Hsinchu
State/Country:	TAIWAN
Postal Code:	300

#### PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13411193

## **CORRESPONDENCE DATA**

 Fax Number:
 (703)518-5499

 Phone:
 7036841111

 Email:
 tsmc@ipfirm.com

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

via US Mail.

Correspondent Name: Lowe Hauptman Ham & Berner, LLP (TSMC)

Address Line 1: 1700 Diagonal Road, Suite 300 Address Line 4: Alexandria, VIRGINIA 22314

ATTORNEY DOCKET NUMBER:	T5057-B580
NAME OF SUBMITTER:	Randy A. Noranbrock

Total Attachments: 1

501840455

source=efiledassgn#page1.tif

PATENT

REEL: 027799 FRAME: 0809

Docket No. T5057-B580 TSMC2011-1031

## ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

- 1) Shiang-Ruei SU
- 2) Liang-Chen LIN
- 3) Chia-wei TU

who has made a certain new and useful invention, hereby sells, assigns and transfers unto

# TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD. having a place of business at No.

## 8, Li-Hsin Rd. VI, Hsinchu Science Park, Hsinchu 300, Taiwan R.O.C.

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

## TEST CHIP, TEST BOARD AND RELIABILITY TESTING METHOD

(a)	for which an application for United States Letters Patent was filed on $2012-03-02$ , States Patent Application No. $13/411$ , $193$ ; or	and	identified	by	United

(b) for which an application for United States Letters Patent was executed on \_\_\_\_\_

and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefore and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside my signature:

1) Shiang - Ruei S Name: Shiang-Ruei SU

RECORDED: 03/02/2012

2) Liang-Chen Lin

3) Chra-Uler Ju.

Mar. 01, 2012

Mar. 0/, 20/2

Mar. 01, >012

PATENT REEL: 027799 FRAME: 0810